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What is "Embedded - Microcontrollers"?

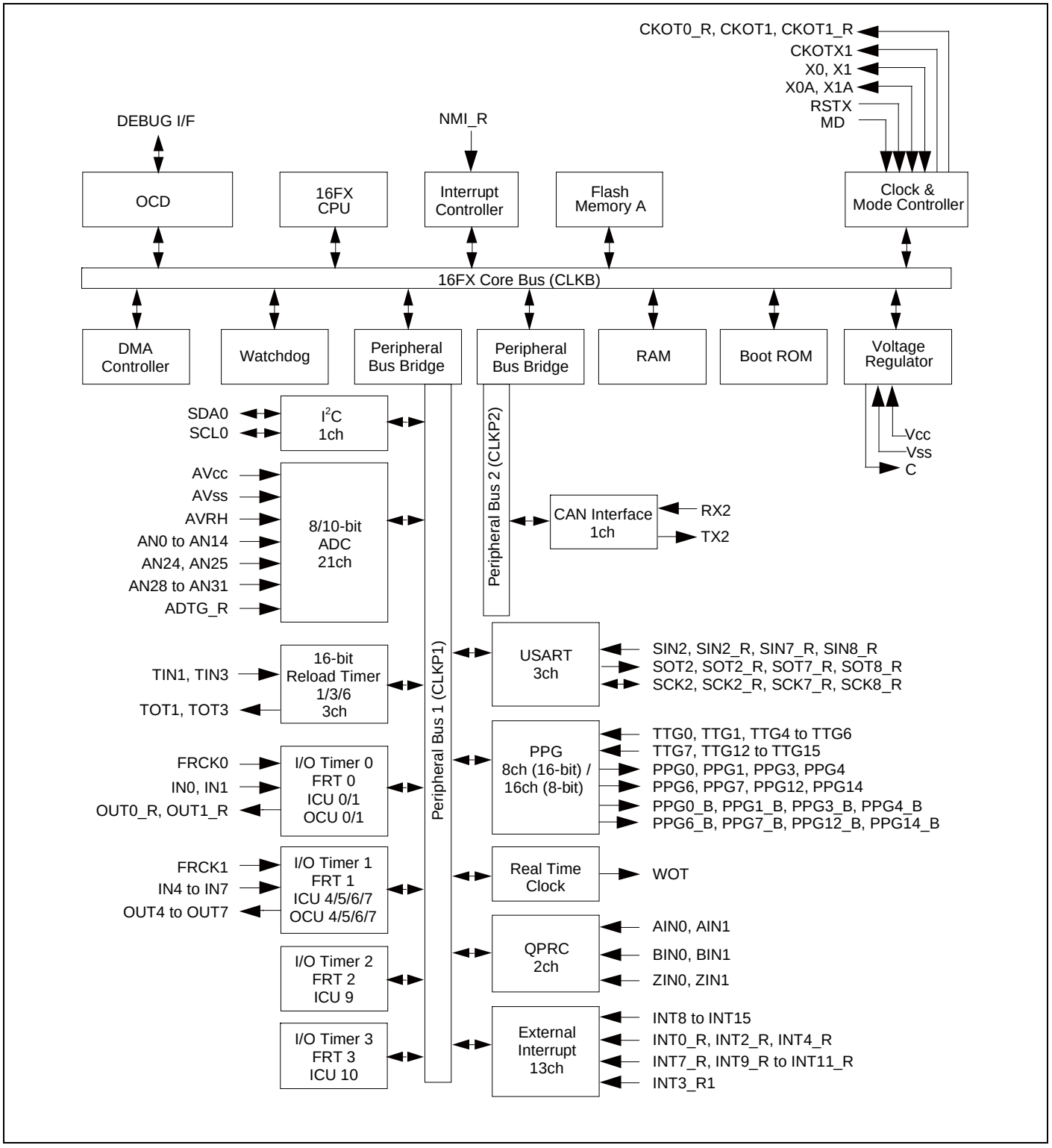
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

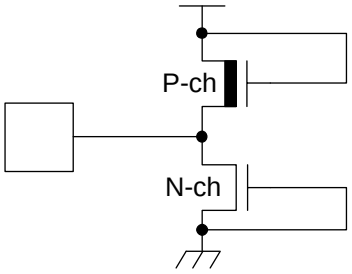
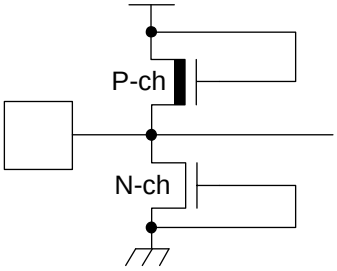
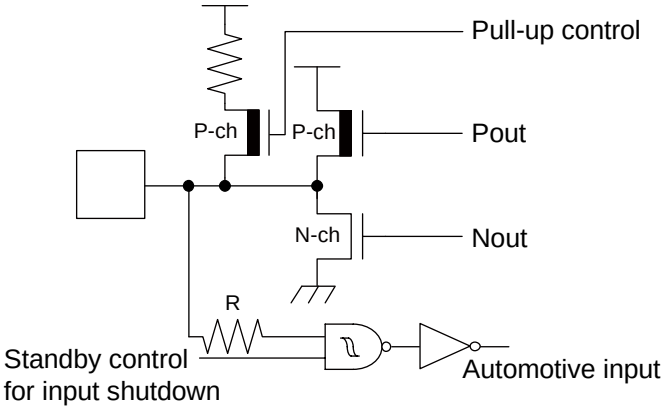
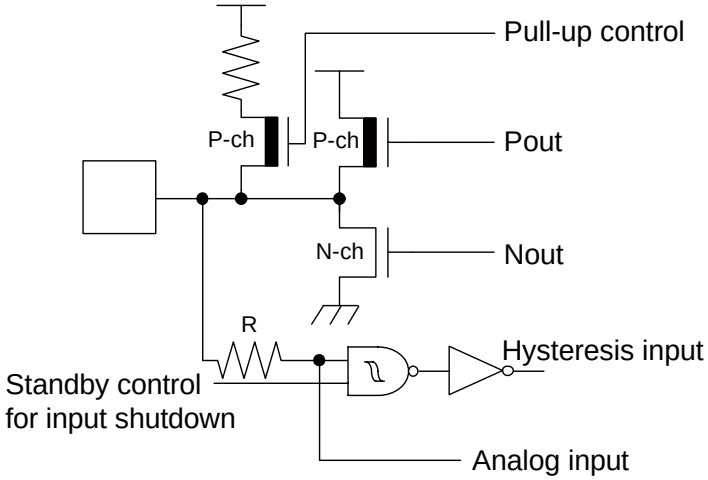
Applications of "Embedded - Microcontrollers"

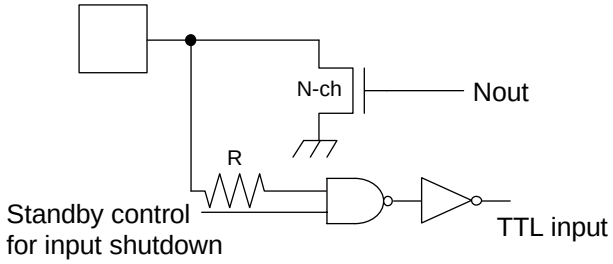
Details	
Product Status	Obsolete
Core Processor	F²MC-16FX
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SCI, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	52
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 21x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb96f623abpmc-gse1

Contents

2. Block Diagram



Type	Circuit	Remarks
F		Power supply input protection circuit
G		• A/D converter ref+ (AVRH) power supply input pin with protection circuit • Without protection circuit against V_{CC} for pins AVRH
H		• CMOS level output (I_{OL} = 4mA, I_{OH} = -4mA) • Automotive input with input shutdown function • Programmable pull-up resistor
I		• CMOS level output (I_{OL} = 4mA, I_{OH} = -4mA) • CMOS hysteresis input with input shutdown function • Programmable pull-up resistor • Analog input

Type	Circuit	Remarks
O		• Open-drain I/O • Output 25mA, Vcc = 2.7V • TTL input

8. RAMSTART Addresses

Devices	Bank 0 RAM size	RAMSTART0
MB96F622	4KB	$00:7200_H$
MB96F623 MB96F625	10KB	$00:5A00_H$

9. User ROM Memory Map For Flash Devices

CPU mode address	Flash memory mode address	MB96F622 Flash size 32.5KB + 32KB	MB96F623 Flash size 64.5KB + 32KB	MB96F625 Flash size 128.5KB + 32KB	
$FF:FFFF_H$ $FF:8000_H$	$3F:FFFF_H$ $3F:8000_H$	SA39 - 32KB	SA39 - 64KB	SA39 - 64KB	Bank A of Flash A
$FF:7FFF_H$ $FF:0000_H$	$3F:7FFF_H$ $3F:0000_H$	Reserved			
$FE:FFFF_H$ $FE:0000_H$	$3E:FFFF_H$ $3E:0000_H$		Reserved	SA38 - 64KB	
$FD:FFFF_H$ $DF:A000_H$				Reserved	
$DF:9FFF_H$ $DF:8000_H$	$1F:9FFF_H$ $1F:8000_H$	SA4 - 8KB	SA4 - 8KB	SA4 - 8KB	Bank B of Flash A
$DF:7FFF_H$ $DF:6000_H$	$1F:7FFF_H$ $1F:6000_H$	SA3 - 8KB	SA3 - 8KB	SA3 - 8KB	
$DF:5FFF_H$ $DF:4000_H$	$1F:5FFF_H$ $1F:4000_H$	SA2 - 8KB	SA2 - 8KB	SA2 - 8KB	
$DF:3FFF_H$ $DF:2000_H$	$1F:3FFF_H$ $1F:2000_H$	SA1 - 8KB	SA1 - 8KB	SA1 - 8KB	
$DF:1FFF_H$ $DF:0000_H$	$1F:1FFF_H$ $1F:0000_H$	SAS - 512B*	SAS - 512B*	SAS - 512B*	Bank A of Flash A
$DE:FFFF_H$ $DE:0000_H$		Reserved	Reserved	Reserved	

*: Physical address area of SAS-512B is from $DF:0000_H$ to $DF:01FF_H$.
Others (from $DF:0200_H$ to $DF:1FFF_H$) is mirror area of SAS-512B.
Sector SAS contains the ROM configuration block RCBA at CPU address $DF:0000_H$ -$DF:01FF_H$.
SAS can not be used for E^2PROM emulation.

12. Handling Precautions

Any semiconductor devices have inherently a certain rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

12.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

■Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of certain established limits, called absolute maximum ratings. Do not exceed these ratings.

■Recommended Operating Conditions

Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their sales representative beforehand.

■Processing and Protection of Pins

These precautions must be followed when handling the pins which connect semiconductor devices to power supply and input/output functions.

1. Preventing Over-Voltage and Over-Current Conditions

   Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such overvoltage or over-current conditions at the design stage.
2. Protection of Output Pins

   Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions if present for extended periods of time can damage the device.
   Therefore, avoid this type of connection.
3. Handling of Unused Input Pins

   Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

■Latch-up

Semiconductor devices are constructed by the formation of P-type and N-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic PNPN junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred mA to flow continuously at the power supply pin. This condition is called latch-up.

CAUTION: The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:

1. Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.
2. Be sure that abnormal current flows do not occur during the power-on sequence.

■Observance of Safety Regulations and Standards

Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

■Fail-Safe Design

Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

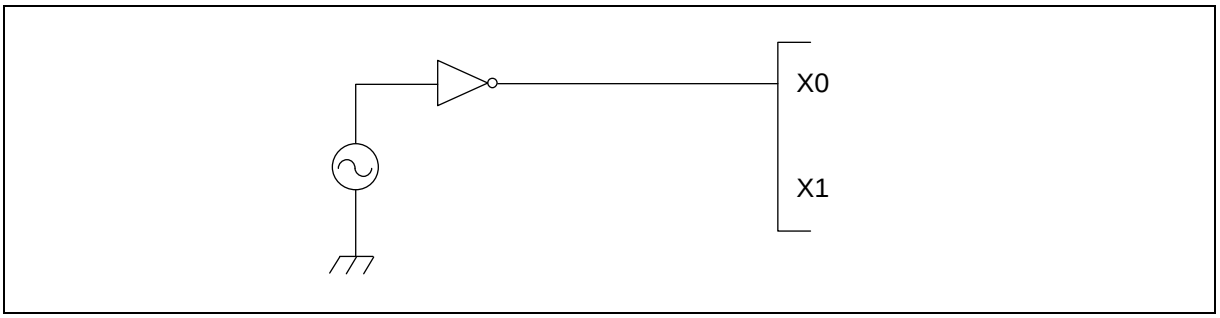
13.3 External clock usage

The permitted frequency range of an external clock depends on the oscillator type and configuration.

See AC Characteristics for detailed modes and frequency limits. Single and opposite phase external clocks must be connected as follows:

13.3.1 Single phase external clock for Main oscillator

When using a single phase external clock for the Main oscillator, X0 pin must be driven and X1 pin left open.
And supply 1.8V power to the external clock.



13.3.2 Single phase external clock for Sub oscillator

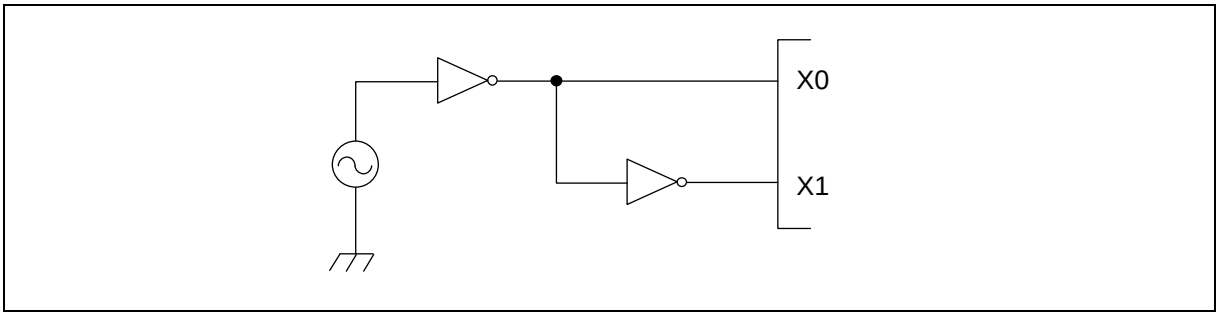
When using a single phase external clock for the Sub oscillator, “External clock mode” must be selected and

X0A/P04_0 pin must be driven. X1A/P04_1 pin can be configured as GPIO.

13.3.3 Opposite phase external clock

When using an opposite phase external clock, X1 (X1A) pins must be supplied with a clock signal which has

the opposite phase to the X0 (X0A) pins. Supply level on X0 and X1 pins must be 1.8V.



13.4 Notes on PLL clock mode operation

If the microcontroller is operated with PLL clock mode and no external oscillator is operating or no external clock is supplied, the microcontroller attempts to work with the free oscillating PLL. Performance of this operation, however, cannot be guaranteed.

13.5 Power supply pins (V_{cc}/V_{ss})

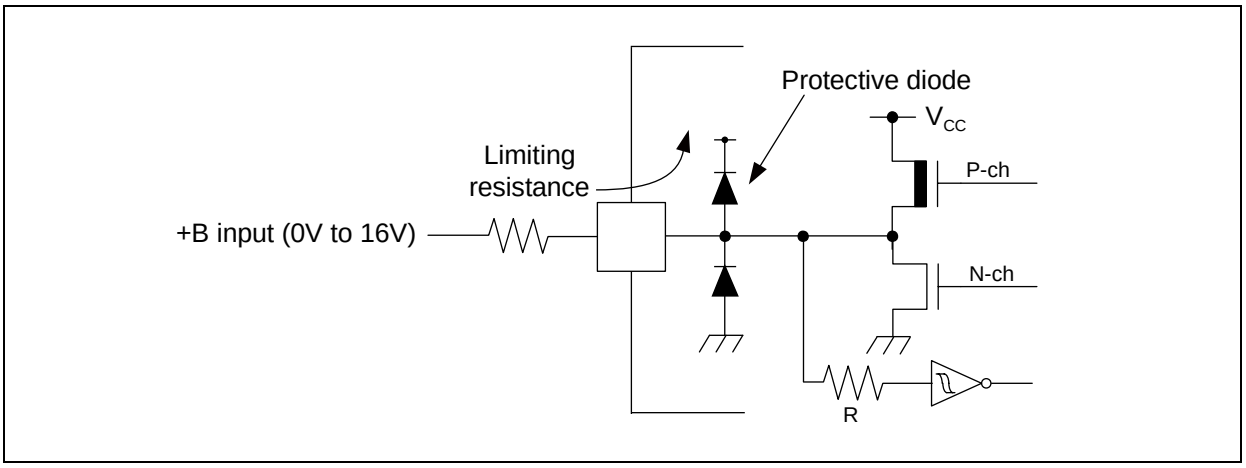
It is required that all V_{CC}-level as well as all V_{SS}-level power supply pins are at the same potential. If there is more than one V_{CC} or V_{SS} level, the device may operate incorrectly or be damaged even within the guaranteed operating range.

V_{cc} and V_{ss} pins must be connected to the device from the power supply with lowest possible impedance.

The smoothing capacitor at V_{cc} pin must use the one of a capacity value that is larger than Cs.

Besides this, as a measure against power supply noise, it is required to connect a bypass capacitor of about 0.1μF between V_{cc} and V_{ss} pins as close as possible to V_{cc} and V_{ss} pins.

- The DEBUG I/F pin has only a protective diode against V_{SS}. Hence it is only permitted to input a negative clamping current (4mA). For protection against positive input voltages, use an external clamping diode which limits the input voltage to maximum 6.0V.
- Sample recommended circuits:



*5: The maximum permitted power dissipation depends on the ambient temperature, the air flow velocity and the thermal conductance of the package on the PCB.
The actual power dissipation depends on the customer application and can be calculated as follows:
$P_D = P_{IO} + P_{INT}$
$P_{IO} = \Sigma (V_{OL} \times I_{OL} + V_{OH} \times I_{OH})$ (I/O load power dissipation, sum is performed on all I/O ports)
$P_{INT} = V_{CC} \times (I_{CC} + I_A)$ (internal power dissipation)
I_{CC} is the total core current consumption into V_{CC} as described in the “DC characteristics” and depends on the selected operation mode and clock frequency and the usage of functions like Flash programming.
I_A is the analog current consumption into AV_{CC}.

*6: Worst case value for a package mounted on single layer PCB at specified T_A without air flow.

*7: Write/erase to a large sector in flash memory is warranted with TA ≤ + 105°C.

WARNING
Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

14.3 DC Characteristics

14.3.1 Current Rating

(V_{CC} = AV_{CC} = 2.7V to 5.5V, V_{SS} = AV_{SS} = 0V, T_A = - 40°C to + 125°C)

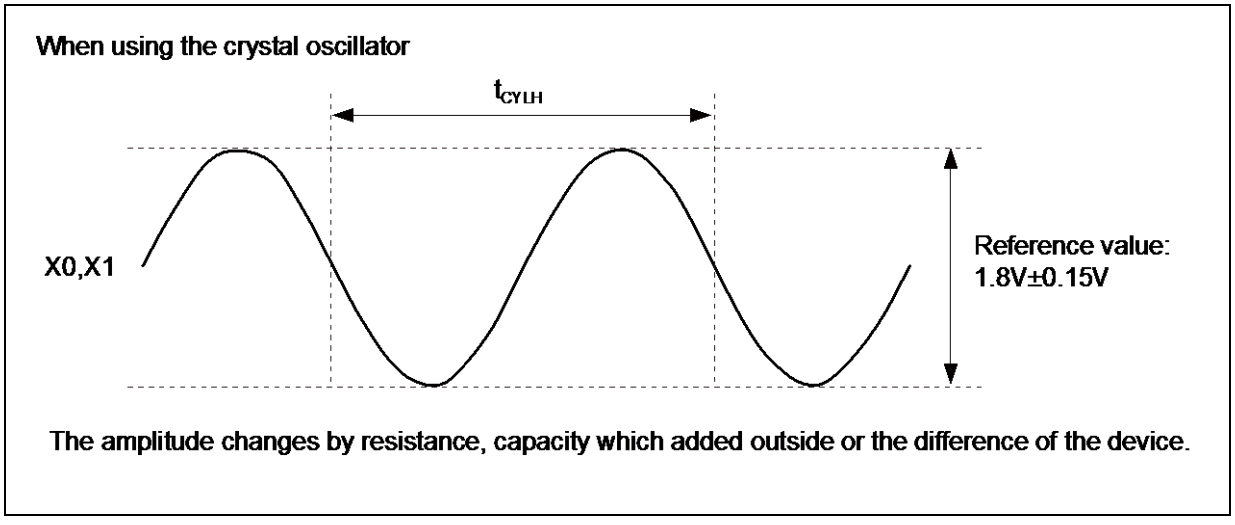
Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Power supply current in Run modes[*1]	I_{CCPLL}	Vcc	PLL Run mode with CLKS1/2 = CLKB = CLKP1/2 = 32MHz Flash 0 wait (CLKRC and CLKSC stopped)	-	25	-	mA	T_A = +25°C
				-	-	34	mA	T_A = +105°C
				-	-	35	mA	T_A = +125°C
	I_{CCMAIN}		Main Run mode with CLKS1/2 = CLKB = CLKP1/2 = 4MHz Flash 0 wait (CLKPLL, CLKSC and CLKRC stopped)	-	3.5	-	mA	T_A = +25°C
				-	-	7.5	mA	T_A = +105°C
				-	-	8.5	mA	T_A = +125°C
	I_{CCRCH}		RC Run mode with CLKS1/2 = CLKB = CLKP1/2 = CLKRC = 2MHz Flash 0 wait (CLKMC, CLKPLL and CLKSC stopped)	-	1.7	-	mA	T_A = +25°C
				-	-	5.5	mA	T_A = +105°C
				-	-	6.5	mA	T_A = +125°C
	I_{CCRCL}		RC Run mode with CLKS1/2 = CLKB = CLKP1/2 = CLKRC = 100kHz Flash 0 wait (CLKMC, CLKPLL and CLKSC stopped)	-	0.15	-	mA	T_A = +25°C
				-	-	3.2	mA	T_A = +105°C
				-	-	4.2	mA	T_A = +125°C
	I_{CCSUB}		Sub Run mode with CLKS1/2 = CLKB = CLKP1/2 = 32kHz Flash 0 wait (CLKMC, CLKPLL and CLKRC stopped)	-	0.1	-	mA	T_A = +25°C
				-	-	3	mA	T_A = +105°C
				-	-	4	mA	T_A = +125°C

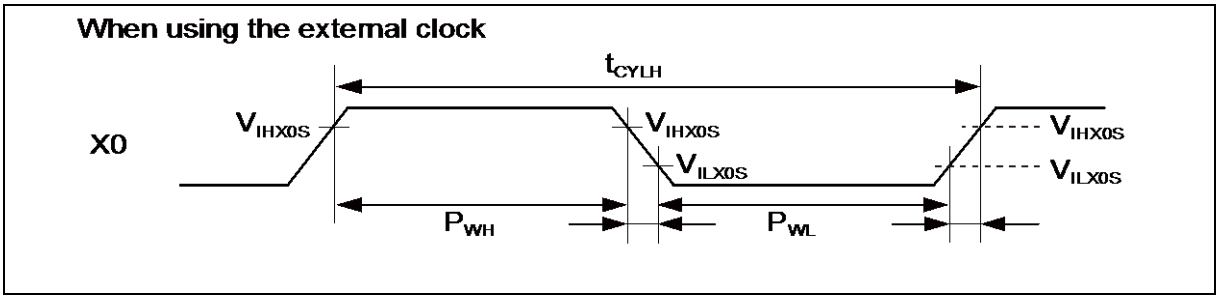
14.4 AC Characteristics

14.4.1 Main Clock Input Characteristics

(V_{CC} = AV_{CC} = 2.7V to 5.5V, VD=1.8V±0.15V, V_{SS} = AV_{SS} = 0V, T_A = - 40°C to + 125°C)

Parameter	Symbol	Pin name	Value			Unit	Remarks
			Min	Typ	Max		
Input frequency	f_C	X0, X1	4	-	8	MHz	When using a crystal oscillator, PLL off
			-	-	8	MHz	When using an opposite phase external clock, PLL off
			4	-	8	MHz	When using a crystal oscillator or opposite phase external clock, PLL on
Input frequency	f_{FCI}	X0	-	-	8	MHz	When using a single phase external clock in “Fast Clock Input mode”, PLL off
			4	-	8	MHz	When using a single phase external clock in “Fast Clock Input mode”, PLL on
Input clock cycle	t_{CYLH}	-	125	-	-	ns	
Input clock pulse width	P_{WH}, P_{WL}	-	55	-	-	ns	

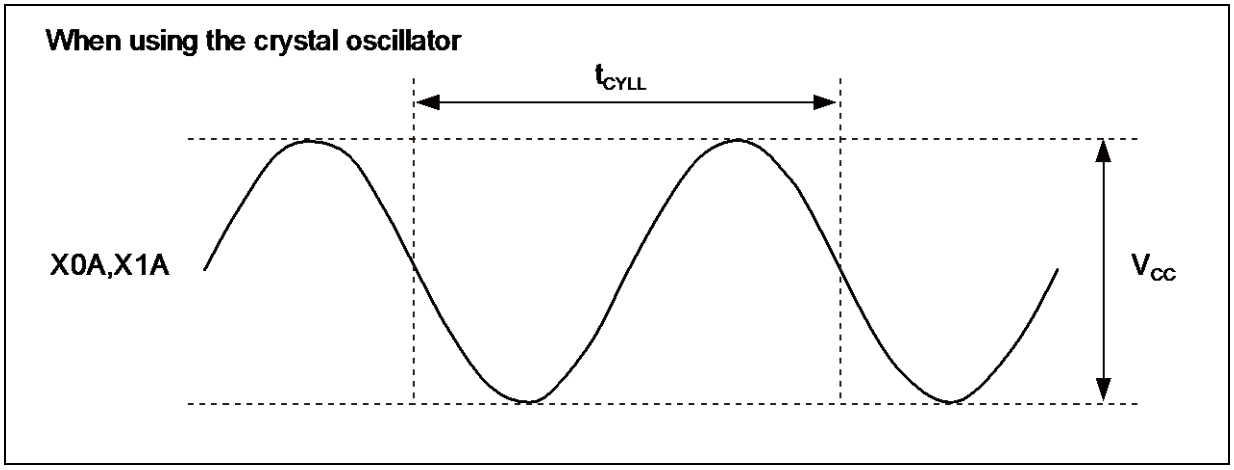


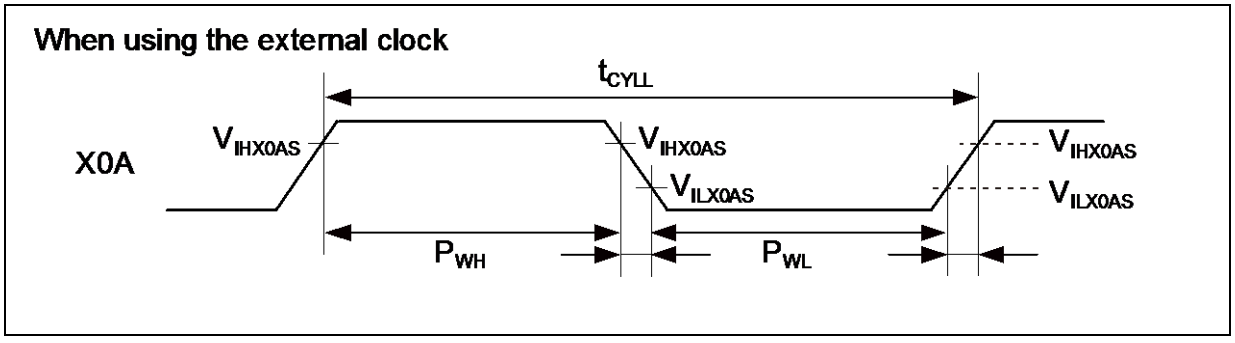


14.4.2 Sub Clock Input Characteristics

(V_{CC} = AV_{CC} = 2.7V to 5.5V, V_{SS} = AV_{SS} = 0V, T_A = - 40°C to + 125°C)

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Input frequency	f_{CL}	X0A, X1A	-	-	32.768	-	kHz	When using an oscillation circuit
			-	-	-	100	kHz	When using an opposite phase external clock
		X0A	-	-	-	50	kHz	When using a single phase external clock
Input clock cycle	t_{CYLL}	-	-	10	-	-	µs	
Input clock pulse width	-	-	P_{WH}/t_{CYLL}, P_{WL}/t_{CYLL}	30	-	70	%	





14.4.3 Built-in RC Oscillation Characteristics

(V_{CC} = AV_{CC} = 2.7V to 5.5V, V_{SS} = AV_{SS} = 0V, T_A = - 40°C to + 125°C)

Parameter	Symbol	Value			Unit	Remarks
		Min	Typ	Max		
Clock frequency	f_{RC}	50	100	200	kHz	When using slow frequency of RC oscillator
		1	2	4	MHz	When using fast frequency of RC oscillator
RC clock stabilization time	t_{RCSTAB}	80	160	320	µs	When using slow frequency of RC oscillator (16 RC clock cycles)
		64	128	256	µs	When using fast frequency of RC oscillator (256 RC clock cycles)

14.4.4 Internal Clock Timing

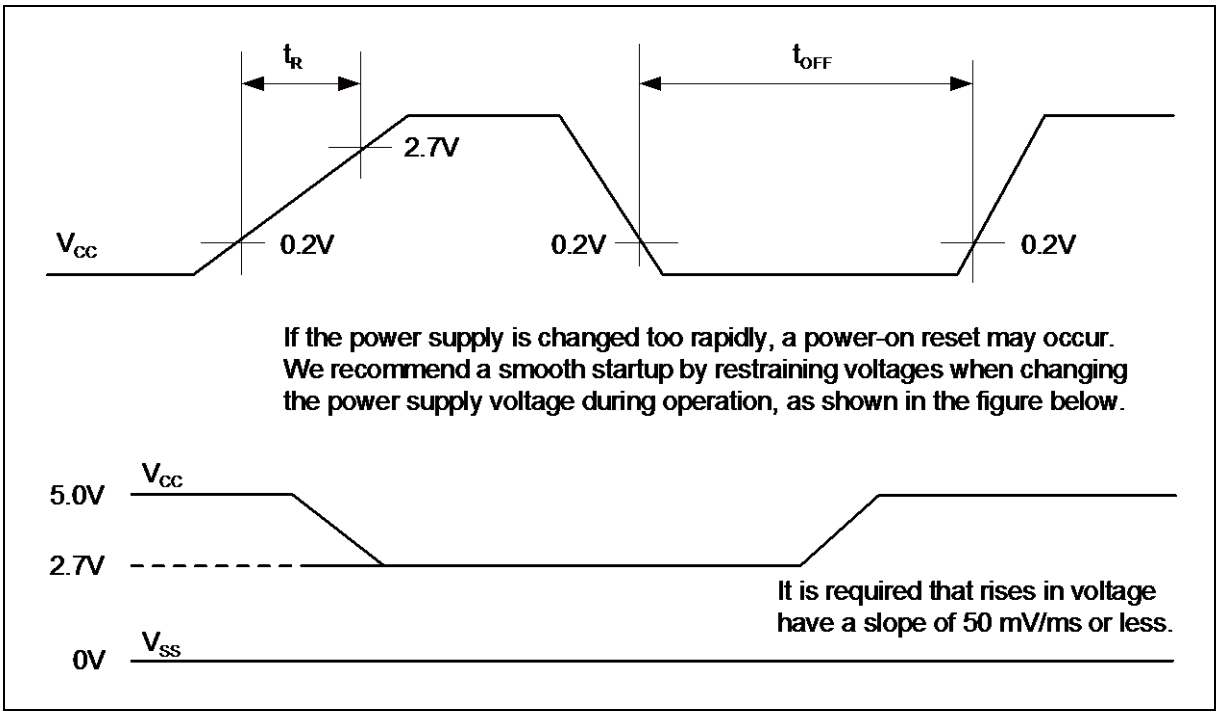
(V_{CC} = AV_{CC} = 2.7V to 5.5V, V_{SS} = AV_{SS} = 0V, T_A = - 40°C to + 125°C)

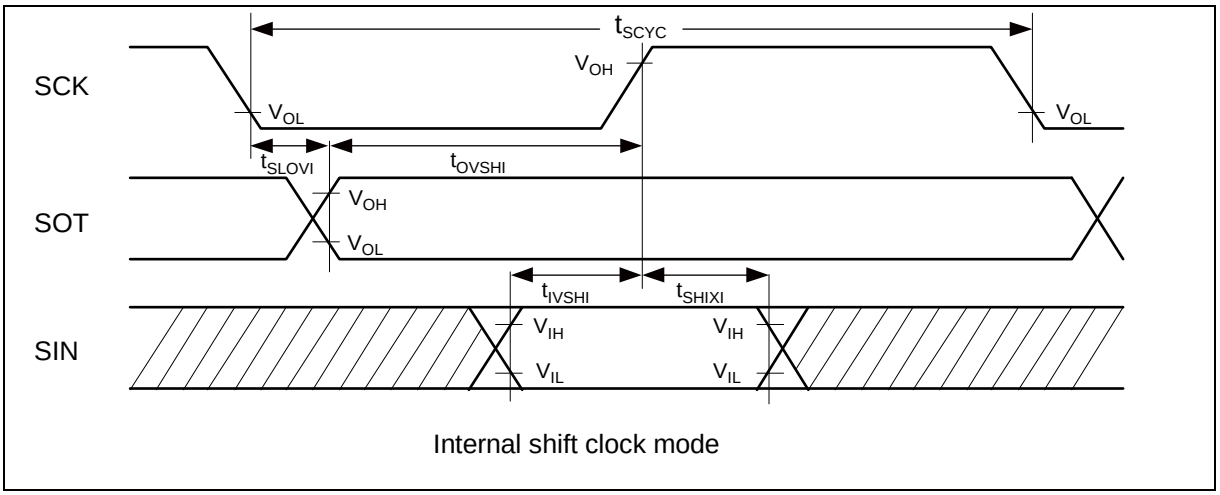
Parameter	Symbol	Value		Unit
		Min	Max	
Internal System clock frequency (CLKS1 and CLKS2)	f_{CLKS1}, f_{CLKS2}	-	54	MHz
Internal CPU clock frequency (CLKB), Internal peripheral clock frequency (CLKP1)	f_{CLKB}, f_{CLKP1}	-	32	MHz
Internal peripheral clock frequency (CLKP2)	f_{CLKP2}	-	32	MHz

14.4.7 Power-on Reset Timing

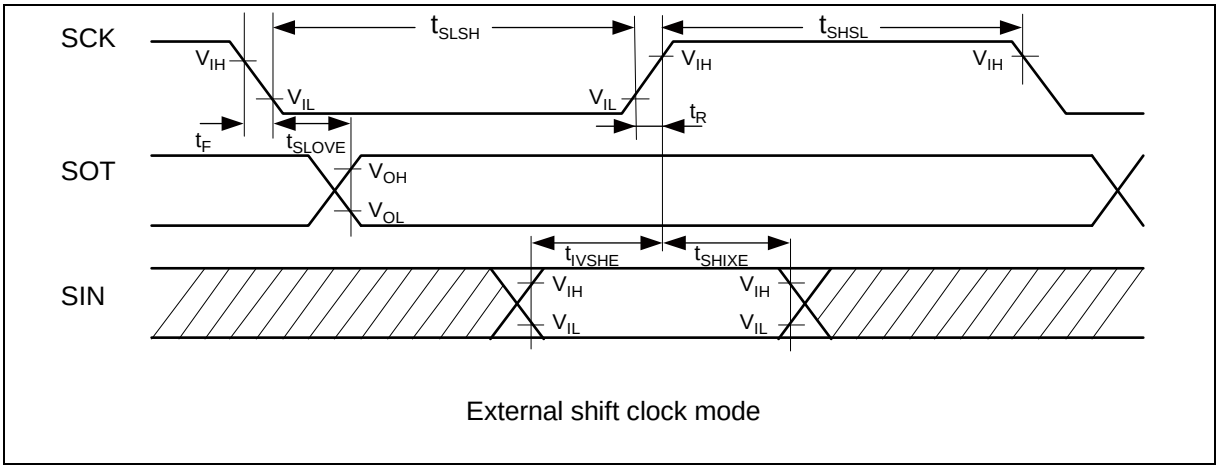
(V_{CC} = AV_{CC} = 2.7V to 5.5V, V_{SS} = AV_{SS} = 0V, T_A = - 40°C to + 125°C)

Parameter	Symbol	Pin name	Value			Unit
			Min	Typ	Max	
Power on rise time	t_R	Vcc	0.05	-	30	ms
Power off time	t_{OFF}	Vcc	1	-	-	ms





Internal shift clock mode

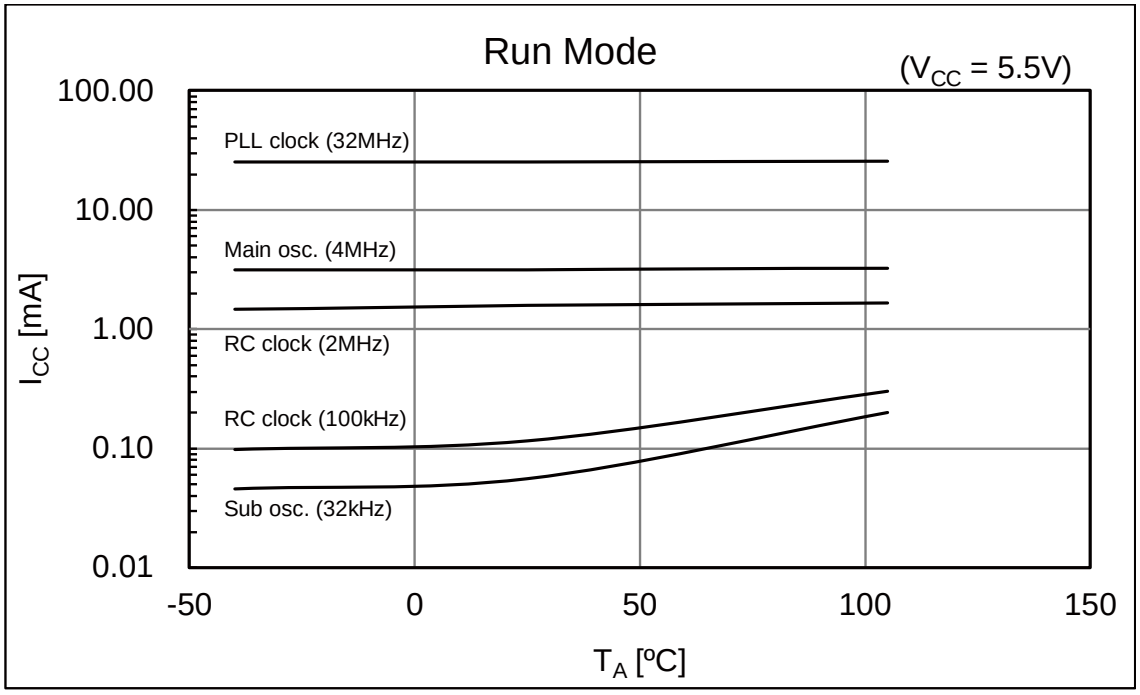


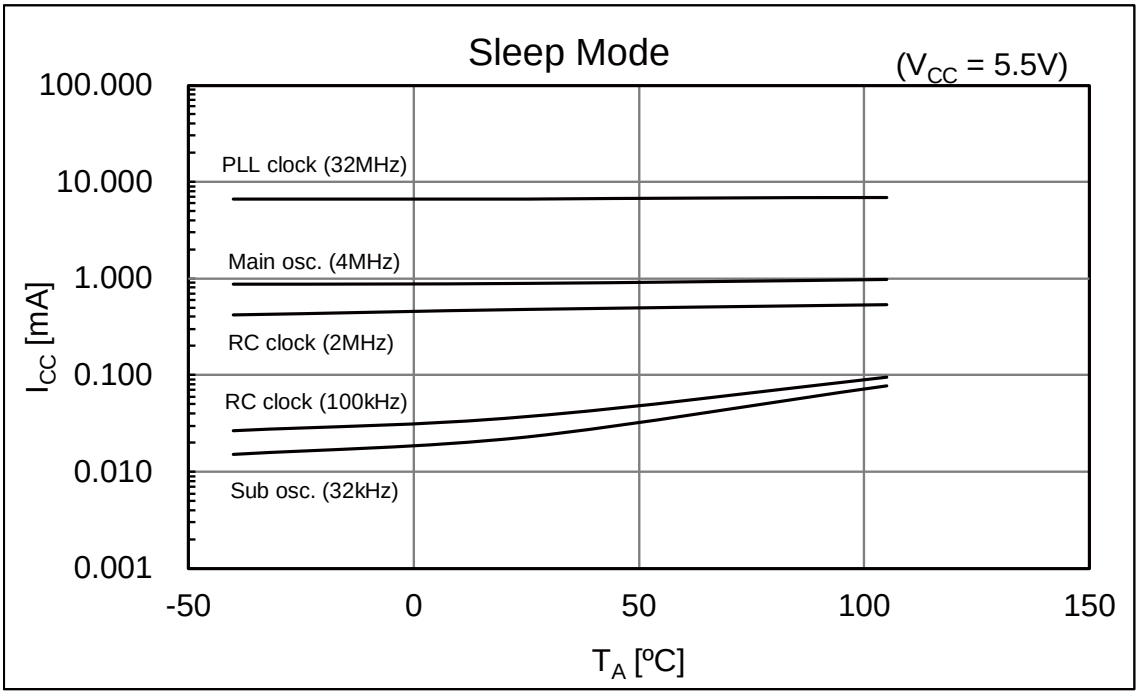
External shift clock mode

15. Example Characteristics

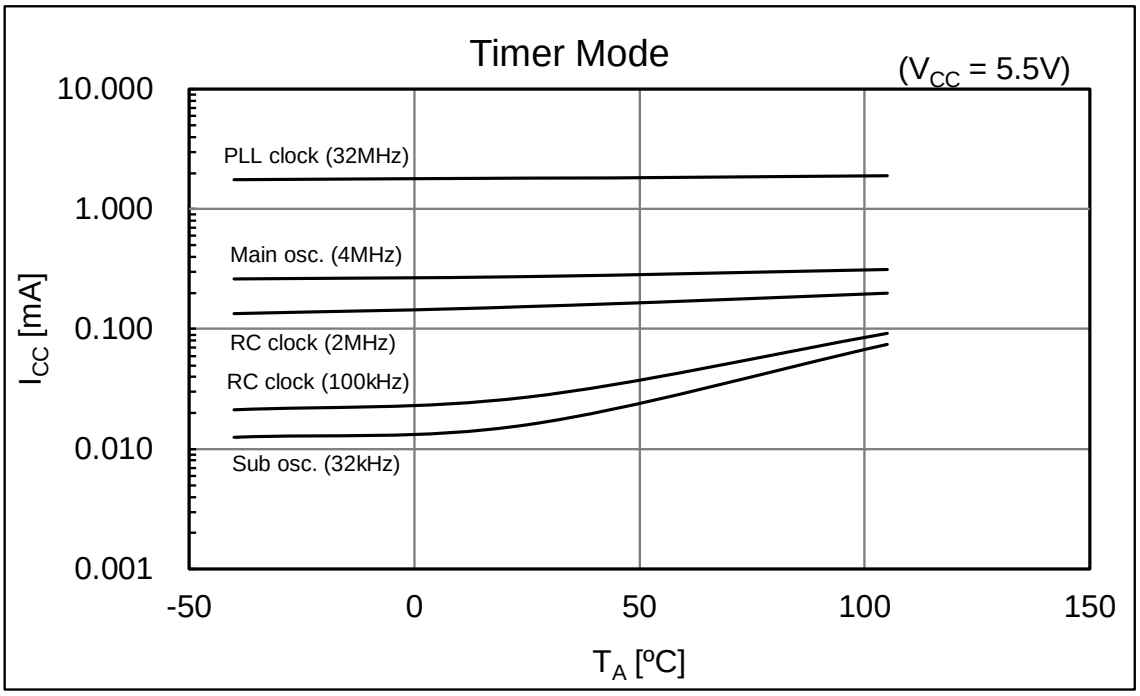
This characteristic is an actual value of the arbitrary sample. It is not the guaranteed value.

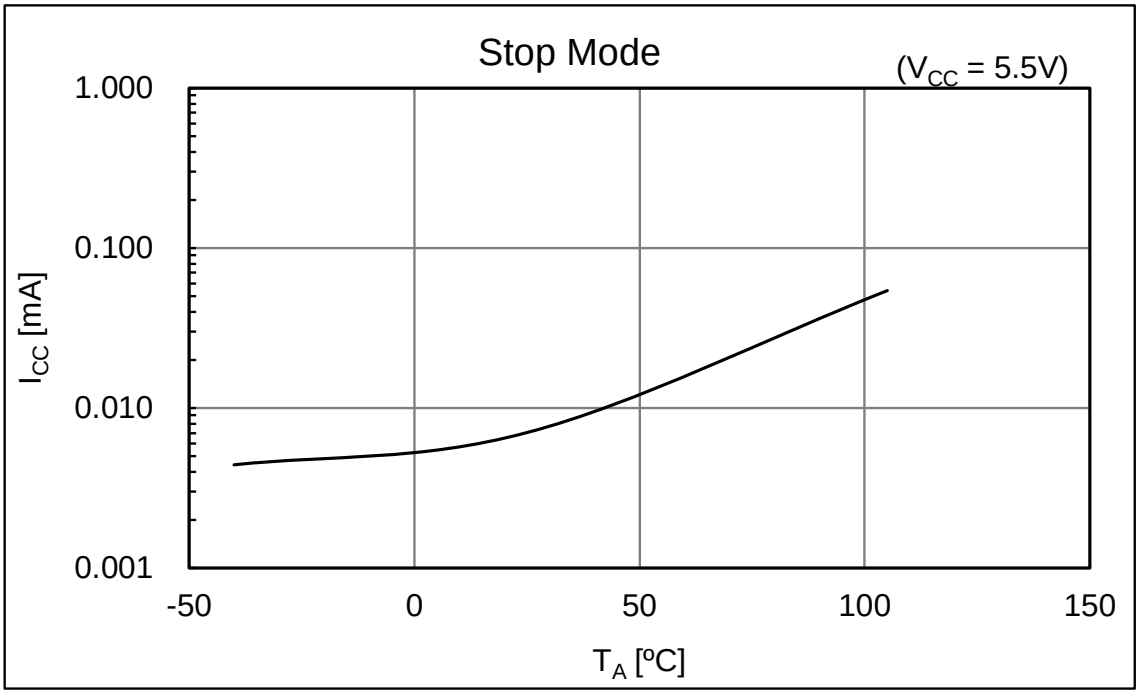
■MB96F625





■MB96F625


Timer Mode
(V_{CC} = 5.5V)
10.000
1.000
0.100
0.010
0.001
I_{CC} [mA]
PLL clock (32MHz)
Main osc. (4MHz)
RC clock (2MHz)
RC clock (100kHz)
Sub osc. (32kHz)
-50
0
50
100
150
T_A [ºC]


Stop Mode
(V_{CC} = 5.5V)
1.000
0.100
0.010
0.001
I_{CC} [mA]
-50
0
50
100
150
T_A [ºC]

16. Ordering Information

MCU with CAN controller

Part number	Flash memory	Package*
MB96F622RBPMC-GSE1	Flash A (64.5KB)	64-pin plastic LQFP (FPT-64P-M23)
MB96F622RBPMC-GSE2		
MB96F622RBPMC-GTE1		
MB96F622RBPMC1-GSE1		64-pin plastic LQFP (FPT-64P-M24)
MB96F622RBPMC1-GSE2		
MB96F622RBPMC1-GTE1		
MB96F623RBPMC-GSE1	Flash A (96.5KB)	64-pin plastic LQFP (FPT-64P-M23)
MB96F623RBPMC-GSE2		
MB96F623RBPMC-GTE1		
MB96F623RBPMC1-GSE1		64-pin plastic LQFP (FPT-64P-M24)
MB96F623RBPMC1-GSE2		
MB96F623RBPMC1-GTE1		
MB96F625RBPMC-GSE1	Flash A (160.5KB)	64-pin plastic LQFP (FPT-64P-M23)
MB96F625RBPMC-GSE2		
MB96F625RBPMC-GTE1		
MB96F625RBPMC1-GSE1		64-pin plastic LQFP (FPT-64P-M24)
MB96F625RBPMC1-GSE2		
MB96F625RBPMC1-GTE1		

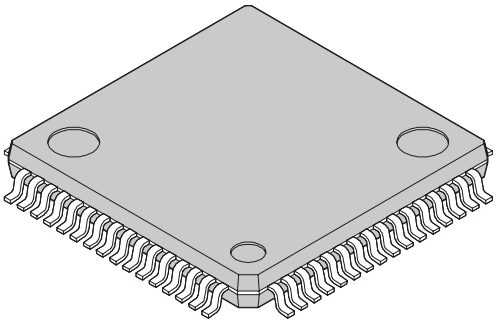
*: For details about package, see "PACKAGE DIMENSION".

MCU without CAN controller

Part number	Flash memory	Package*
MB96F622ABPMC-GSE1	Flash A (64.5KB)	64-pin plastic LQFP (FPT-64P-M23)
MB96F622ABPMC-GSE2		
MB96F622ABPMC-GTE1		
MB96F622ABPMC1-GSE1		64-pin plastic LQFP (FPT-64P-M24)
MB96F622ABPMC1-GSE2		
MB96F622ABPMC1-GTE1		
MB96F623ABPMC-GSE1	Flash A (96.5KB)	64-pin plastic LQFP (FPT-64P-M23)
MB96F623ABPMC-GSE2		
MB96F623ABPMC-GTE1		
MB96F623ABPMC1-GSE1		64-pin plastic LQFP (FPT-64P-M24)
MB96F623ABPMC1-GSE2		
MB96F623ABPMC1-GTE1		
MB96F625ABPMC-GSE1	Flash A (160.5KB)	64-pin plastic LQFP (FPT-64P-M23)
MB96F625ABPMC-GSE2		
MB96F625ABPMC-GTE1		
MB96F625ABPMC1-GSE1		64-pin plastic LQFP (FPT-64P-M24)
MB96F625ABPMC1-GSE2		
MB96F625ABPMC1-GTE1		

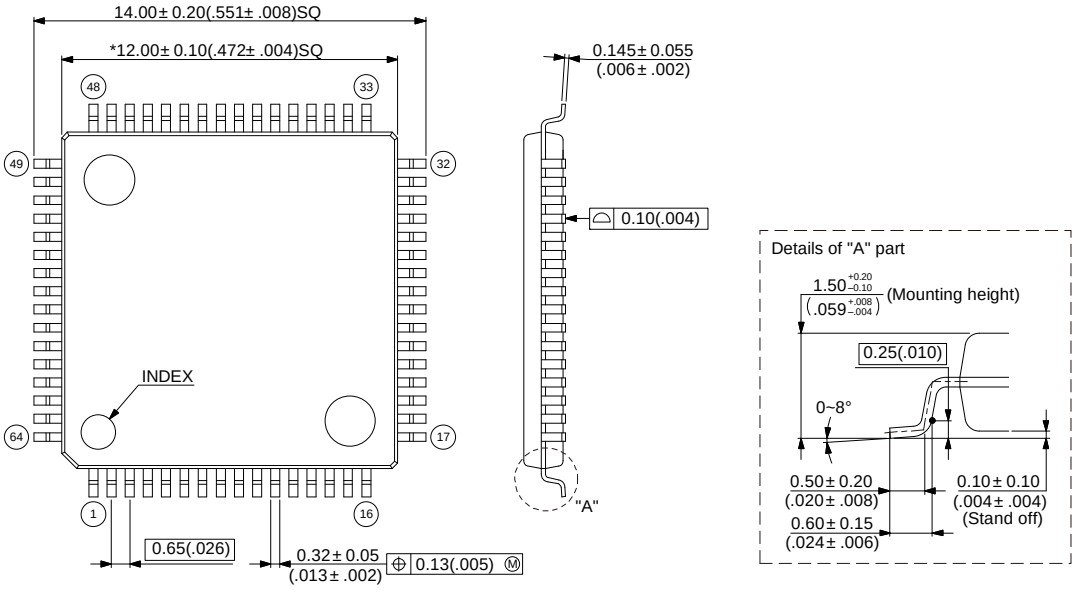
*: For details about package, see "PACKAGE DIMENSION".

17. Package Dimension

64-pin plastic LQFP		
	Lead pitch	0.65 mm
	Package width × package length	12.0 × 12.0 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	1.70 mm MAX
	Weight	0.47 g
(FPT-64P-M23)	Code (Reference)	P-LQFP64-12 × 12-0.65

64-pin plastic LQFP
(FPT-64P-M23)

Note 1) * : These dimensions do not include resin protrusion.
Note 2) Pins width and pins thickness include plating thickness.
Note 3) Pins width do not include tie bar cutting remainder.



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Dimensions in mm (inches).
Note: The values in parentheses are reference values